



Final Product Change Notification

201405016F01

Issue Date: 21-May-2014
Effective Date: 19-Aug-2014

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QUALITY

Management Summary

The display driver PCA85134H//Q900/1 will be assembled with copper (Cu) bond wires instead of gold (Au).

Change Category

<input type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

PCA85134H/Q900/1 will change the wire bond material from Au to Cu

Details of this Change

The display driver PCA85134H//Q900/1 will be assembled with copper (Cu) bond wires instead of gold (Au). The currently available version with gold wire will be discontinued.

Why do we Implement this Change

- To align with world technology trends
- To use wiring with enhanced mechanical and electrical properties

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 18-Aug-2014

Impact

no impact to the product's functionality anticipated.
ESD CDM-value will change to 1000V from currently 1500V.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Jun-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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